



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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NOTES :

1- MATERIAL:

-HOUSING: LCP FIBER GLASS FILLED UL 94-V0 COLOR BLACK.

-TERMINAL: PHOSPHOR BRONZE

PLATING:

BASE FINISH: NICKEL

CONTACT SURFACE FINISH:

GOLD,

OR

GOLD FLASH OVER PALLADIUM NICKEL.

EXCEEDS PRODUCT REQUIREMENTS BASED ON PS-85507-001

-SHIELD: COPPER ALLOY PLATED WITH TIN

2- JACK FOR MATING WITH IEC 60603-7 AND TIA-1096-A SHIELDED PLUGS (95043 MOLEX SERIES).

3- PRODUCT SPECIFICATION PS-85507-001

4- PACKAGING SPECIFICATION PK-95022 (TRAY PACKAGING).

5- EXCEEDS CATEGORY 5E PERFORMANCE.

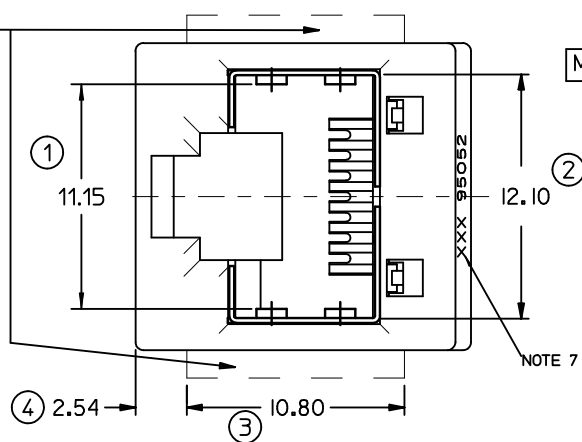
6- PC BOARD THICKNESS: 1.57

7- MANUFACTURING I.D. CAN BE MG, MXF OR MXI.

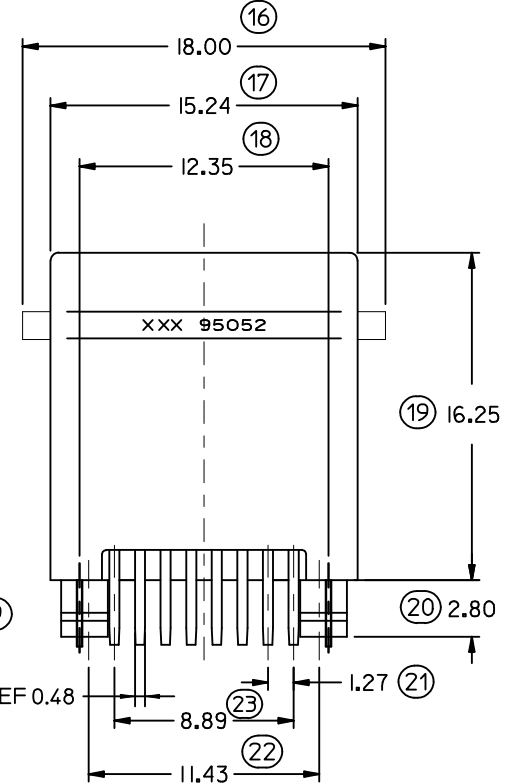
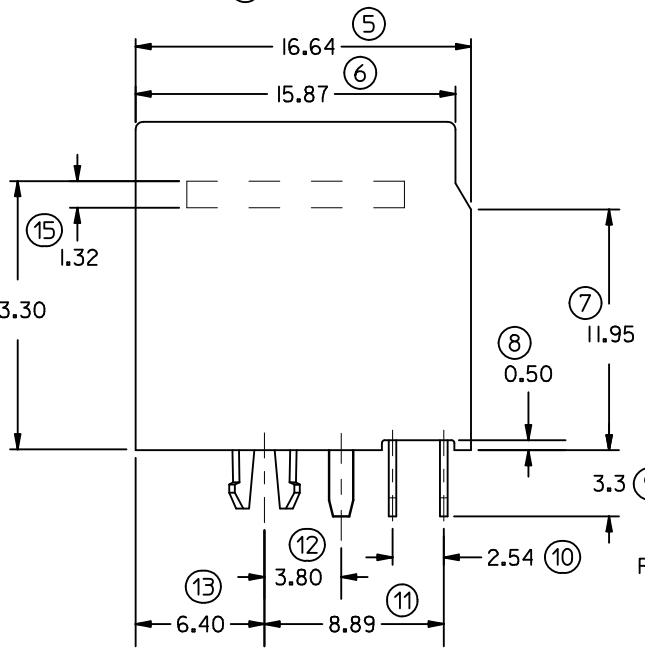
8- APPLICATION SPECIFICATION: AS-85513-001

9- LAST INSPECTON NUMBER 23

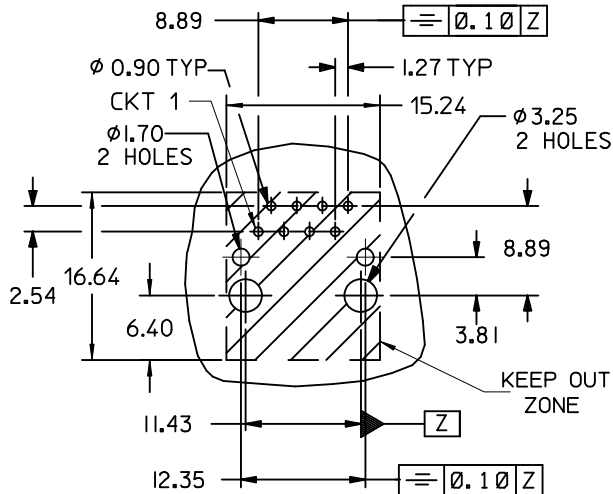
OPTIONAL RIBS



	JACKS WITH RIBS	JACKS WITHOUT RIBS
MATERIAL No.	85507-5001	85507-5002



P.C.B. MOUNTING PATTERN
(View from component side)
SCALE 2:1



ALL DIMENSIONS REFERENCE ONLY

REMOVED PLATING OPTIONS EC NO: IPG2012-0700 DRW:DBYRMS 2012/04/03 CHKD:MSHAHAN 2012/04/17 APPR:EFOLAN 2012/06/28	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY FB	DATE 98/08/05	TITLE TOP ENTRY HIGH SPEED SHIELDED MODULAR JACK THROUGH HOLE 8 CIRCUIT			
		4 PLACES	± ---	± ---	CHECKED BY FM	DATE 98/08/05	MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY FB	DATE 98/08/05	MATERIAL NO. SEE CHART DOCUMENT NO. SD-85507-501 SHEET NO. 1 OF 1			
			2 PLACES	± 0.15	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			1 PLACE	± 0.25	± ---					
			ANGULAR ± 2 °							
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								